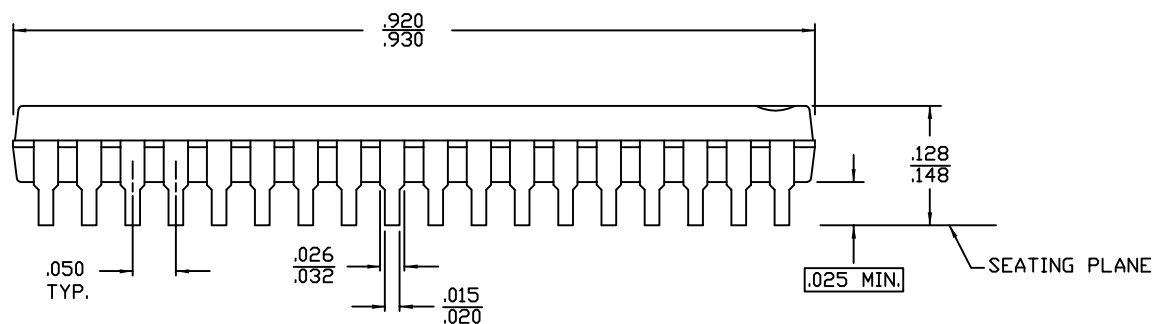
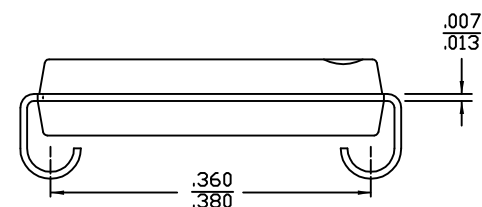
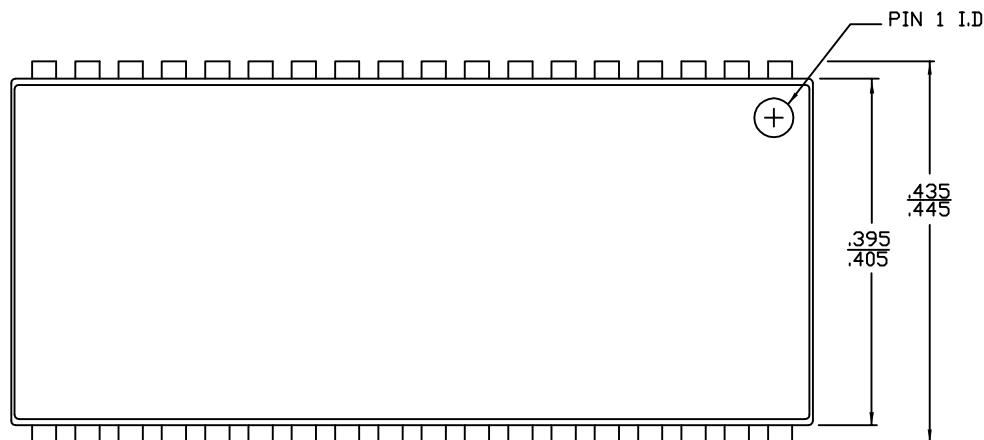



36 Lead (400 MIL) Molded SOJ V36

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
		**	48093	NEW RELEASE	01/13/97	
		*A	57335	CHG. PKG. THICK DIM.	08/07/98	
		*B	64703	PKG. THICKNESS OPTION	10/15/99	
		*C	498426	CHANGE OVERALL PACKAGE THICKNESS/CHANGE STANDOFF MIN:HEIGHT	08/30/06	
1	-	*D	2779863	CHANGED TO STANDARD DRAWING FORMAT	10/07/09	TSV
1	-			CHANGED TITLE FROM 36.4 SOJ PKG. OUTL.-DATA BOOK TO PACKAGE OUTLINE, 36L SOJ V36.4 (MOLDED)		
1	D4	*E	3022278	ADD GENERAL TOLERANCE 0.05 TO THE TITLE HEADER	09/03/10	TSV



DIMENSIONS IN INCHES MIN.
MAX.

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON:		DESIGNED BY	DATE	 CYPRESS Company Confidential	
DECIMALS	ANGLES	DRAWN BY	DATE		
.XX ± 0.05	± 1°	TZWTF1	10/07/09	TITLE	
.XXX ±		CHECKED BY	DATE		
.XXXX +		TSV	10/07/09	PACKAGE OUTLINE, 36L SOJ V36.4 (MOLDED)	
		APPROVED BY	DATE		
		QAD	10/07/09	SIZE A PART NO. V36.4 DWG NO 51-85090 REV *E	
		APPROVED BY	DATE		
		CMG	10/07/09	SCALED TO FIT SHEET 1 OF 1	
		APPROVED BY	DATE		